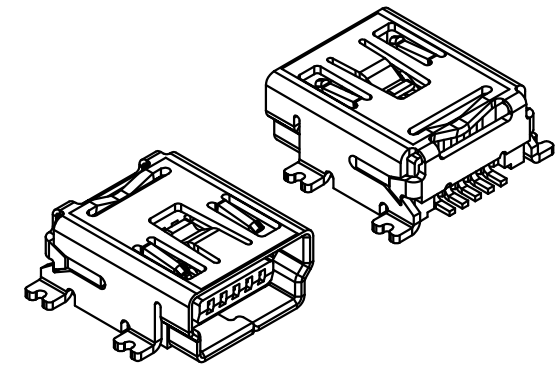


|      |                       |         |      |
|------|-----------------------|---------|------|
| REV. | ECN NO OR DESCRIPTION | REVISED | DATE |
|------|-----------------------|---------|------|

SPECIFICATIONS:  
SEE "2UB-MB01 SERIES SPECIFICATIONS".



PART NO.

2UB-MB01-□□1

SHELL PLATING  
B: TIN-LEAD(霧錫)  
C: TIN-LEAD(亮錫)  
BODY/POST  
0: YES  
1: NO

| NO | DESCRIPTION | QTY | MATERIAL                                | PLATING & COLOR  |
|----|-------------|-----|---|--|
| 4  | MYLAR       | 1   |   |  |
| 3  | SHELL       | 1   | HIGH PERFORMANCE COPPER ALLOY 0.4t      | TIN-LEAD OVER NICKEL   |
| 2  | CONTACT     | 5   | HIGH PERFORMANCE COPPER ALLOY 0.25t     | GOLD 30u" OVER NICKEL IN CONTACT AREA<br>TIN-LEAD OVER NICKEL IN SOLDER TAIL |
| 1  | HOUSING     | 1   | HIGH TEMP. THERMOPLASTIC UL<br>UL 94V-0 | BLACK COLOR  |

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.  
信音企業股份有限公司

|             |         |       |                        |                       |              |
|-------------|---------|-------|------------------------|-----------------------|--------------|
| DECIMALS:   | ANGLES: | TITLE | USB MINI-B TYPE(5 PIN) |                       |              |
| X.X :±0.25  |         | DWN   | Even 7/12-'04          | PART NO. 2UB-MB01-□□1 |              |
| X.XX :±0.13 |         | CHKD  | Kan 7/12-'04           | SCALE:4/1             | UNIT: MM     |
|             |         | APVD  | Andrew 7/13-'04        | SIZE: A3              | SHEET:1 OF 1 |

PCB LAYOUT  
TOLERANCES:±0.05